


- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material;
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: Giga-snaP BGA SMT Foot
400 position terminal pins (0.8mm centers, 20x20 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA400H-B-61F Drawing	Status: Released	Scale: 5:1	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: A. Evans		Date: 05/28/09
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